

In re Patent Application of:
MAGNI ET AL.
Serial No. 10/036,335
Filing Date: DECEMBER 26, 2001

In the Claims:

Claims 1-7 (Cancelled).

8. (Currently Amended) A method for forming a plastic protective package for an integrated circuit, the integrated circuit being at least partially activated from outside of the protective package, the method comprising:

positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an insert projecting towards the inside of the mold, the insert being elastically deformable based upon fluid pressure against a back face thereof and abutting in pressing contact against at least one portion of the integrated circuit; and

injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

9. (Previously Presented) A method according to Claim 8, further comprising supplying pressure to the insert.

Claim 10 (Cancelled).

11. (Previously Presented) A method according to Claim 9, wherein the half-mold has an opening therein for connection to a pressure source.

12. (Previously Presented) A method according to Claim 8, wherein the at least one portion comprises a border portion of the integrated circuit.

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13. (Previously Presented) A method according to Claim 8, wherein the insert comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

14. (Currently Amended) A method for forming a plastic protective package for an integrated circuit, the method comprising:

positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an elastically deformable membrane projecting towards the inside of the mold;

supplying fluid pressure against a back face of to ~~urge~~ the elastically deformable membrane ~~into~~ for pressing into contact against at least one portion of the integrated circuit; and

injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

Claim 15 (Cancelled).

16. (Previously Presented) A method according to Claim 14, wherein the half-mold has an opening therein for connection to a pressure source.

17. (Previously Presented) A method according to Claim 14, wherein the at least one portion comprises a border portion of the integrated circuit.

18. (Previously Presented) A method according to

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Claim 14, wherein the elastically deformable membrane comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

Claims 19-25 (Cancelled).